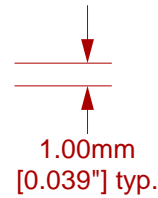
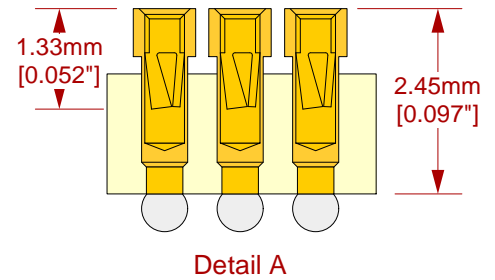
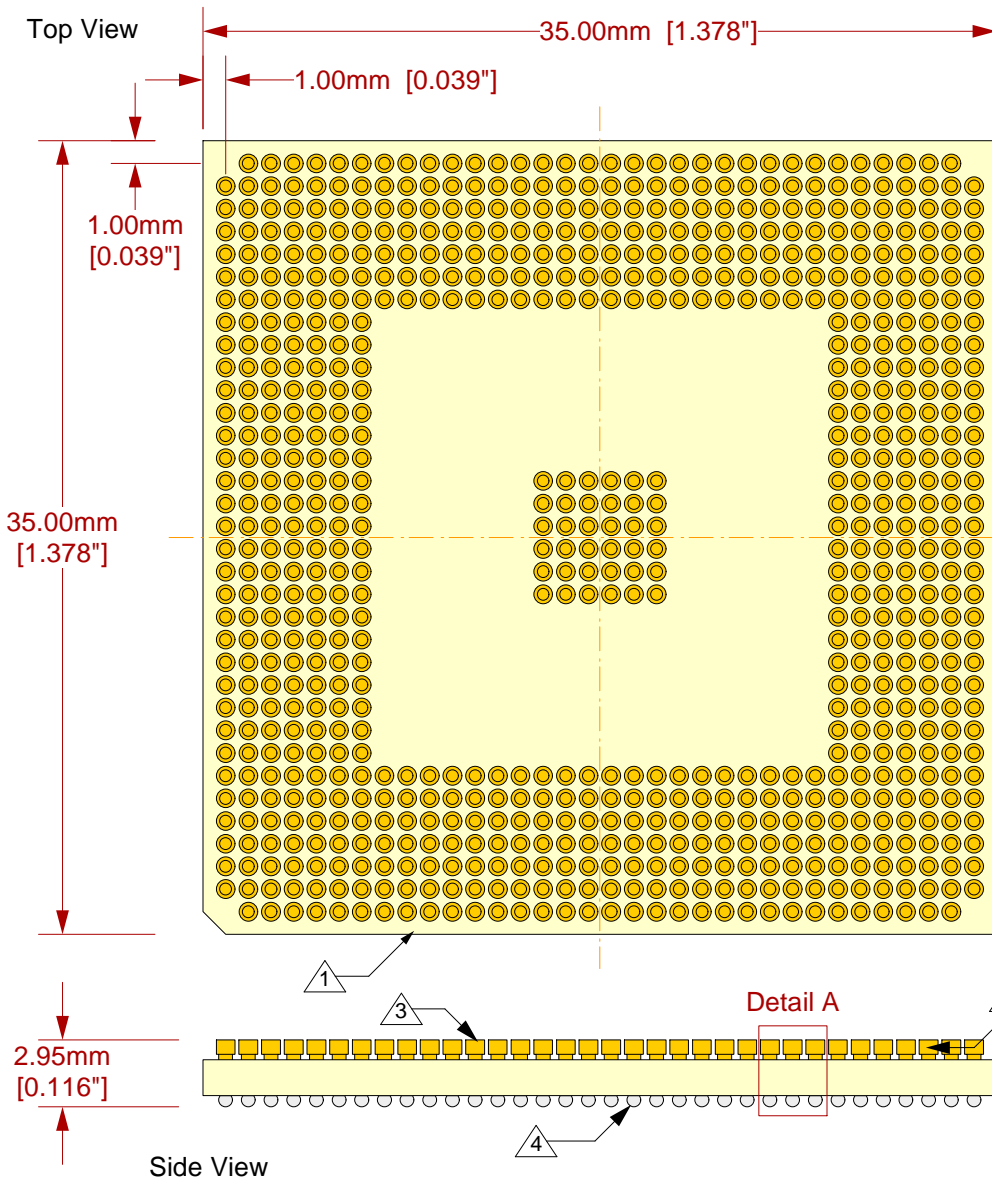


Patent Pending



Ordering Information:

Solder Ball Alloy	Part Number Suffix
Sn63Pb37	-42
Sn96.5Ag3.0Cu0.5	-42F*

*RoHS Compliant

- ① Substrate: 1.59mm \pm 0.18mm [0.0625" \pm 0.007"] FR4/G10 or equivalent high temp material.
- ② Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25 μ m [10 μ] Au over 1.27 μ m [50 μ] Ni (min.).
- ③ Contacts: Beryllium Copper Alloy172, HT; Finish- 0.25 μ m [10 μ] Au over 1.27 μ m [50 μ] Ni (min.).
- ④ Solder Balls: See Table Above.


CONTACT DATA

Accepts 0.20mm - 0.33mm Diameter pins
 3-finger
 37/25 gram, Initial insertion force (with 0.254mm/0.203mm dia. pin)
 30/22 gram, normal force (with 0.254mm/0.203mm dia. pin)
 20/17 gram, extraction force (with 0.254mm/0.203mm dia. pin)

Description: Giga-snaP BGA SMT Foot

788 position (1.0mm pitch) gold plated female receptacle pins to SMT solder balls (BGA type). Pin assignment 1:1.

Tolerances: diameters \pm 0.03mm [\pm 0.001"], PCB perimeters \pm 0.13mm [\pm 0.005"], PCB thicknesses \pm 0.18mm [\pm 0.007"], pitches (from true position) \pm 0.08mm [\pm 0.003"], all other tolerances \pm 0.13mm [\pm 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-BGA788B-B-42(F) Drawing		Status: Released	Scale: 3:1	Rev: A
 <p>© 2006 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Drawing: H. Hansen		Date: 9/25/06	
	File: SF-BGA788B-B-42 Dwg		Modified:	